

N-CHANNEL ENHANCEMENT MOS FET

ABSOLUTE MAXIMUM RATINGS			
PARAMETER	SYMBOL		UNITS
DRAIN-SOURCE VOLTAGE	VDSS	400	Vdc
DRAIN-GATE VOLTAGE (R _{GS} =1.0M Ω)	VDGR	400	Vdc
GATE-SOURCE VOLTAGE CONTINUOUS	VGS	± 20	Vdc
DRAIN CURRENT CONTINUOUS (T _c = 25°C)	ID	100	Adc
DRAIN CURRENT PULSED	IDM	400	A
TOTAL POWER DISSIPATION	PD	833	W
POWER DISSIPATION DERATING > 25°C		6.67	W/°C
OPERATING & STORAGE TEMP.	TJ/Tsig	-55 TO +150	°C
THERMAL RESISTANCE	RthJc	0.15	°C/W
MAX. LEAD TEMPERATURE	TL	300	°C

400V, 100A, 0.05 Ω

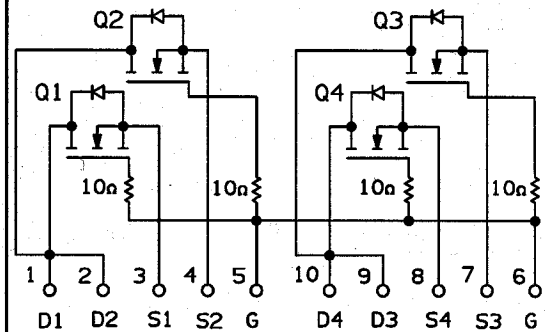
SDF100NA40 HI
SDF100NA40 JD

FEATURES

- RUGGED PACKAGE
- HI-REL CONSTRUCTION
- CERAMIC EYELETS
- LEAD BENDING OPTIONS
- COPPER CORED 52 ALLOY PINS
- LOW IR LOSSES
- LOW THERMAL RESISTANCE
- OPTIONAL MIL-STD-883 SCREENING

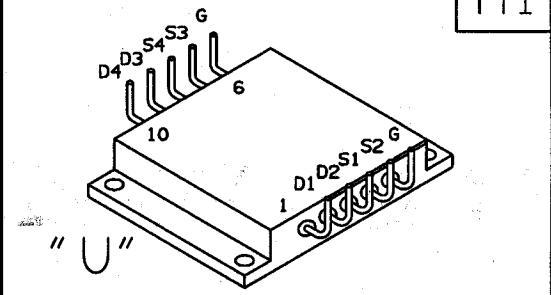
ELECTRICAL CHARACTERISTICS T _c = 25°C (UNLESS OTHERWISE SPECIFIED)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
DRAIN-SOURCE BREAKDOWN VOLTAGE (1 & 2)	V(BR)DSS	VGS=0V ID=250 μ A	400	-	-	V
GATE THRESHOLD VOLTAGE	VGS(TH)	VDS=VGS ID=250 μ A	2.0	-	4.0	V
GATE SOURCE LEAKAGE	IGSS	VGS= ± 20 V	-	-	100	nA
ZERO GATE VOLTAGE DRAIN CURRENT	IDSS	VDS=MAX.RATING VGS=0	-	-	250	μ A
		VDS=0.8 MAX.RATING VGS=0 T _J =125°C	-	-	1000	μ A
STATIC DRAIN-SOURCE ON-STATE RESISTANCE (2)	RDS(ON)	VGS=10 V ID=13A	-	-	0.20	Ω
FORWARD TRANS-CONDUCTANCE (2)	g _{fs}	VDS \geq 50 V IDS=13A	14	-	-	S(V)
INPUT CAPACITANCE	CISS		-	4100	-	pF
OUTPUT CAPACITANCE	COSS	VGS=0V VDS=25 V f=1.0 MHz (3)	-	480	-	pF
REVERSE TRANSFER CAPACITANCE	CRSS		-	84	-	pF
TURN-ON DELAY	t _{d(on)}	VDD=200V RG=4.3 Ω ID=25A RD=7.5 Ω	-	-	33	ns
RISE TIME	t _r	(MOSFET SWITCHING TIMES ARE ESSENTIALLY INDEPENDENT OF OPERATING TEMP. NOTE 3)	-	-	140	ns
TURN-OFF DELAY	t _{d(off)}		-	-	120	ns
FALL TIME	t _f		-	-	99	ns
TOTAL GATE CHARGE (GATE-SOURCE PLUS GATE-DRAIN)	Q _g	VGS=10V, ID=25A VDS=0.8 MAX.RATING (GATE CHARGE IS ESSENTIALLY INDEPENDENT OF THE OPERATING TEMPERATURE NOTE 3)	-	-	190	nC
GATE SOURCE CHARGE	Q _{gs}		-	-	27	nC
GATE-DRAIN (*MILLER*) CHARGE	Q _{gd}		-	-	93	nC

SCHEMATIC



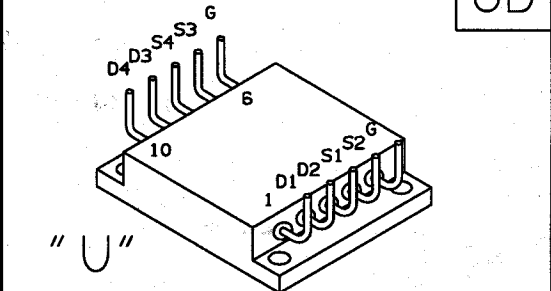
(CUSTOM SCHEMATIC OPTIONS AVAILABLE)

STANDARD BEND CONFIGURATION **HI**



(CUSTOM BEND OPTIONS AVAILABLE)

STANDARD BEND CONFIGURATION **JD**



(CUSTOM BEND OPTIONS AVAILABLE)

TOTAL MODULE RATINGS AND CHARACTERISTICS T _c = 25°C (UNLESS OTHERWISE SPECIFIED)					
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	MAX.	UNITS
PIN-CASE ISOLATION	PCI	V _{CASE} -PINS ALL PINS SHORTED TO CASE	10	-	m Ω
STATIC DRAIN-SOURCE ON-STATE VOLTAGE	VDS(ON)	VGS \geq 10V ID = 100A	-	5.0	V
STATIC DRAIN-SOURCE ON-STATE RESISTANCE	RDS(ON)	VGS = 10V ID = 50A	-	0.05	OHM
ZERO GATE VOLTAGE DRAIN CURRENT	IDSS	VGS = 0V VDS = 400V	-	1.0	mA

(1) T_J = 25°C TO 150°C.
(2) PULSE TEST: PULSE WIDTH < 300 μ S, DUTY CYCLE < 2%.
(3) TEST ARE PERFORMED AT ELEMENT EVALUATION. TEST CONDITIONS AND LIMITS APPLY TO EACH MOSFET SEPARATELY.